



Taiwan Semiconductor

1A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- · Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- · General purpose

MECHANICAL DATA

· Case: Thin SMA

Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test

Polarity: Indicated by cathode band

• Weight: 0.029g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	1	А	
V_{RRM}	200 - 1000	V	
I _{FSM}	30	Α	
T _{J MAX}	150	°C	
Package	Thin SMA		
Configuration	Single die		







Thin SMA



PARAMETER		SYMBOL	RS1DAL	RS1GAL	RS1JAL	RS1KAL	RS1MAL	UNIT
Marking code on the devi	се		RS1DAL	RS1GAL	RS1JAL	RS1KAL	RS1MAL	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I _F	1				Α	
Surge peak forward current single half sine wave superimposed on rated load $t = 8.3 \text{ms}$ $t = 1.0 \text{ms}$		l			30			Α
		I _{FSM}	100					Α
Junction temperature		T_J	-55 to +150			ô		
Storage temperature		T _{STG}	-55 to +150		°C			



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	19	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	81	°C/W	
Junction-to-case thermal resistance	R _{eJC}	19	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
	RS1DAL RS1GAL RS1JAL	$I_F = 0.5A, T_J = 25^{\circ}C$	V _F	0.90	-	V
		$I_F = 1.0A, T_J = 25^{\circ}C$		0.97	1.30	V
		I _F = 0.5A, T _J = 125°C		0.75	-	V
Forward voltage ⁽¹⁾		I _F = 1.0A, T _J = 125°C		0.83	0.94	V
Forward voltage	RS1KAL RS1MAL	I _F = 0.5A, T _J = 25°C		0.96	-	V
		$I_F = 1.0A, T_J = 25^{\circ}C$		1.04	1.30	V
		I _F = 0.5A, T _J = 125°C		0.80	-	V
		I _F = 1.0A, T _J = 125°C		0.90	1.11	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C		-	1	μΑ
		T _J = 125°C	l _R	-	33	μΑ
	RS1DAL RS1GAL	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t _{rr}	-	150	ns
Reverse recovery time	RS1JAL			-	250	ns
	RS1KAL RS1MAL	3.207		-	500	ns
Junction capacitance		1MHz, $V_R = 4.0V$	CJ	7	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
RS1xAL	Thin SMA	14,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 200V(RS1DAL) to 1000V(RS1MAL)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

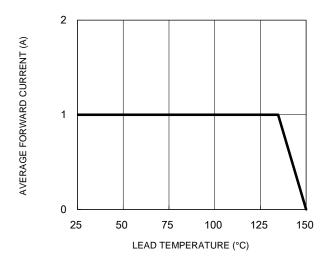


Fig.3 Typical Reverse Characteristics

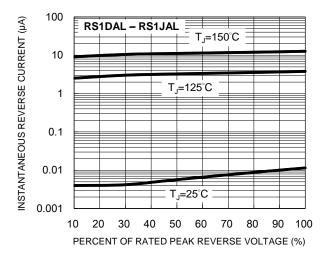


Fig.5 Typical Reverse Characteristics

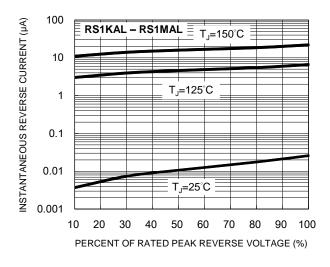


Fig.2 Typical Junction Capacitance

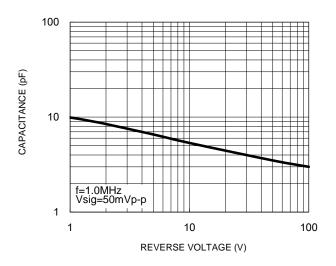


Fig.4 Typical Forward Characteristics

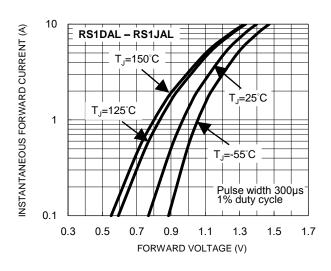
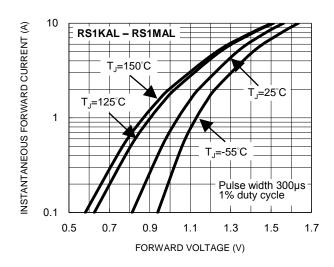


Fig.6 Typical Forward Characteristics

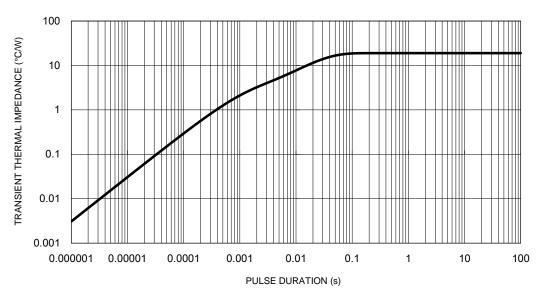


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CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

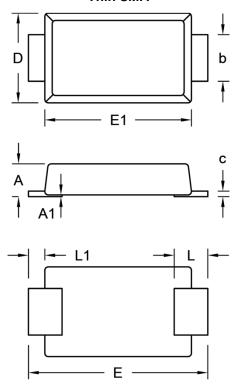
Fig.7 Typical Transient Thermal Impedance





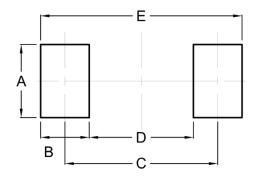
PACKAGE OUTLINE DIMENSIONS

Thin SMA



DIM.	Unit (mm)		Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.
Α	0.90	1.00	0.035	0.039
A1	0.00	0.10	0.000	0.004
b	1.25	1.45	0.049	0.057
С	0.10	0.22	0.004	0.009
D	2.50	2.70	0.098	0.106
E	5.05	5.35	0.199	0.211
E1	4.15	4.35	0.163	0.171
L	0.75	1.20	0.030	0.047
L1	0.30	0.60	0.012	0.024

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



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